关鹏 | GUAN PENG

2026届硕士候选人 · 半导体系统工程 | 2026 M.S. Candidate · Semiconductor Systems Engineering

目标岗位：设备工程师 / 工艺工程师 / 工艺整合工程师 | Target: Equipment / Process / Process Integration

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教育背景 | Education

Sejong University（世宗大学），韩国首尔
半导体系统工程 硕士 | M.S. in Semiconductor Systems Engineering
2025.03 – 2026.12

Shenyang Ligong University（沈阳理工大学），中国
机械设计制造及其自动化 学士 | B.E. in Mechanical Design, Manufacturing and Automation
2016.09 – 2020.07

联系方式 | Contact

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- 所在地：Seoul, South Korea

奖学金 | Scholarship

- 世宗大学外国人留学生奖学金（20% 学费减免）| International Student Scholarship (20% tuition reduction), Spring 2025
- 世宗大学外国人留学生奖学金（20% 学费减免）| International Student Scholarship (20% tuition reduction), Spring 2026

技能 | Skills

- 英文技术文献阅读与整理 | English technical literature review
- 数据整理与技术报告撰写 | Data organization and technical reporting
- Word / Excel / PowerPoint
- 跨文化学习与环境适应 | Cross-cultural learning adaptability

语言能力 | Languages

- 中文：母语 | Chinese: Native
- 英语：学术读写能力 | English: Academic reading & writing
- 韩语：日常交流 | Korean: Basic communication

个人概况 | Profile

- 机械设计制造本科 + 半导体系统工程硕士在读，具备设备结构、实验分析与半导体器件研究交叉背景 | Cross-disciplinary foundation spanning equipment structure, experimental analysis, and semiconductor device research.
- 求职方向聚焦半导体设备、工艺与工艺整合岗位，关注设备稳定性、参数优化、制程分析与制造改善 | Targeting semiconductor equipment, process, and process integration roles with long-term interest in stability, optimization, and manufacturing improvement.

核心优势 | Core Strengths

- 存储器与薄膜方向课程基础突出 | Strong coursework foundation in memory devices and thin-film engineering.
- 第一作者综述论文修订中，主题为 $CsPbI_3$ 忆阻器与神经形态计算 | First-author review manuscript under revision on $CsPbI_3$ memristive devices for neuromorphic computing.
- 具备英文文献对比、图表整合与技术逻辑梳理能力 | Able to synthesize English literature, organize figures/tables, and structure technical narratives.
- 具备设备结构设计、动力分配优化与实验对比分析经验 | Experience in equipment structure design, power optimization, and comparative experimental analysis.
- 具备韩语日常沟通能力，便于在韩国学习、实验室协作与日常交流 | Able to communicate in Korean for daily study, lab coordination, and routine communication in Korea.

半导体相关课程 | Semiconductor Coursework

- 已完成：半导体材料分析（A+）、纳米半导体器件合成及应用（A+）
- 已完成：存储半导体器件（A0）、模拟电路设计（A+）、薄膜工艺及分析（A0）
- Completed: Semiconductor Materials Analysis (A+), Nano Semiconductor Device Synthesis and Applications (A+)
- Completed: Memory Semiconductor Devices (A0), Analog Circuit Design (A+), Thin Film Processing and Analysis (A0)
- 正在修读：硕士论文研究 1、新型存储器件、高级薄膜工程
- In Progress: Master's Thesis Research 1, Emerging Memory Device, Advanced Thin Film Engineering

论文与研究成果 | Publication

第一作者综述论文（修订中）| First-Author Review Manuscript, Under Revision
Performance $CsPbI_3$ Memristive Devices for Neuromorphic Computing: Materials Engineering, Device Physics, and Synaptic Functionality

- 覆盖材料工程、器件物理、阻变机理、类突触功能与阵列应用潜力 | Covers materials engineering, device physics, resistive switching, synaptic functionality, and array-level application potential.
- 完成文献对比、图表整合与技术梳理 | Completed literature comparison, figure/table integration, and technical synthesis.

项目与研究经历 | Project & Research Experience

- 半导体器件制作实习（计划参加，2026.05）：Hyojung Kim 教授研究室，高丽大学自然校区 | Semiconductor device fabrication training (scheduled, May 2026): Prof. Hyojung Kim's lab, Korea University Science Campus.
- 钢筋弯曲机设计：设计二级可变速弯曲机构并优化动力分配 | Rebar bending machine design: designed a two-stage variable-speed bending mechanism and optimized power distribution.
- 本科科研助理：开展高速切削对比实验并分析参数影响 | Undergraduate research assistant: conducted comparative high-speed machining experiments and analyzed process-related factors.